



Low-Noise, High-Speed, 16-Bit Accurate, CMOS OPERATIONAL AMPLIFIER

FEATURES

- High Bandwidth: 150MHz
- 16-Bit Settling in 150ns
- Low Noise: $3nV/\sqrt{Hz}$
- Low Distortion: 0.003%
- Low Power: 9.5mA (typ) on 5.5V
- Shutdown to $5\mu A$
- Unity-Gain Stable
- Excellent Output Swing:
(V+) – 100mV to (V–) + 100mV
- Single Supply: +2.7V to +5.5V
- Tiny Packages: MSOP and SOT23

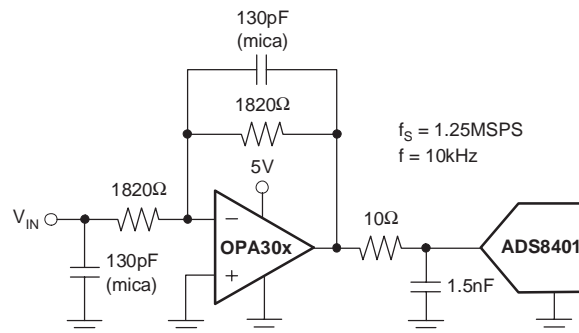
APPLICATIONS

- 16-Bit ADC Input Drivers
- Low-Noise Preamplifiers
- IF/RF Amplifiers
- Active Filtering

DESCRIPTION

The OPA300 and OPA301 series high-speed, voltage-feedback, CMOS operational amplifiers are designed for 16-bit resolution systems. The OPA300/OPA301 series are unity-gain stable and feature excellent settling and harmonic distortion specifications. Low power applications benefit from low quiescent current. The OPA300 and OPA2300 feature a digital shutdown (Enable) function to provide additional power savings during idle periods. Optimized for single-supply operation, the OPA300/OPA301 series offer superior output swing and excellent common-mode range.

The OPA300 and OPA301 series op amps have 150MHz of unity-gain bandwidth, low $3nV/\sqrt{Hz}$ voltage noise, and 0.1% settling within 30ns. Single-supply operation from 2.7V ($\pm 1.35V$) to 5.5V ($\pm 2.75V$) and an available shutdown function that reduces supply current to $5\mu A$ are useful for portable low-power applications. The OPA300 and OPA301 are available in SO-8 and SOT-23 packages. The OPA2300 is available in MSOP-10, and the OPA2301 is available in SO-8 and MSOP-8. All versions are specified over the industrial temperature range of $-40^{\circ}C$ to $+125^{\circ}C$.



Typical Application



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING
OPA300	SO-8	D	300A
OPA300	SOT23-6	DBV	A52
OPA301	SO-8	D	301A
OPA301	SOT23-5	DBV	AUP
OPA2300	MSOP-10	DGS	C01
OPA2301	SO-8	D	OPA2301A
OPA2301	MSOP-8	DGK	OAWM

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

Power Supply V+	7V
Signal Input Terminals(2), Voltage	0.5V to (V+) + 0.5V
Current	±10mA
Open Short-Circuit Current(3)	Continuous
Operating Temperature Range	-55°C to +125°C
Storage Temperature Range	-60°C to +150°C
Junction Temperature	+150°C
ESD Ratings	
Human Body Model (HBM)	4kV
Charged-Device Model (CDM)	500V

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
- (2) Input terminals are diode clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground; one amplifier per package.

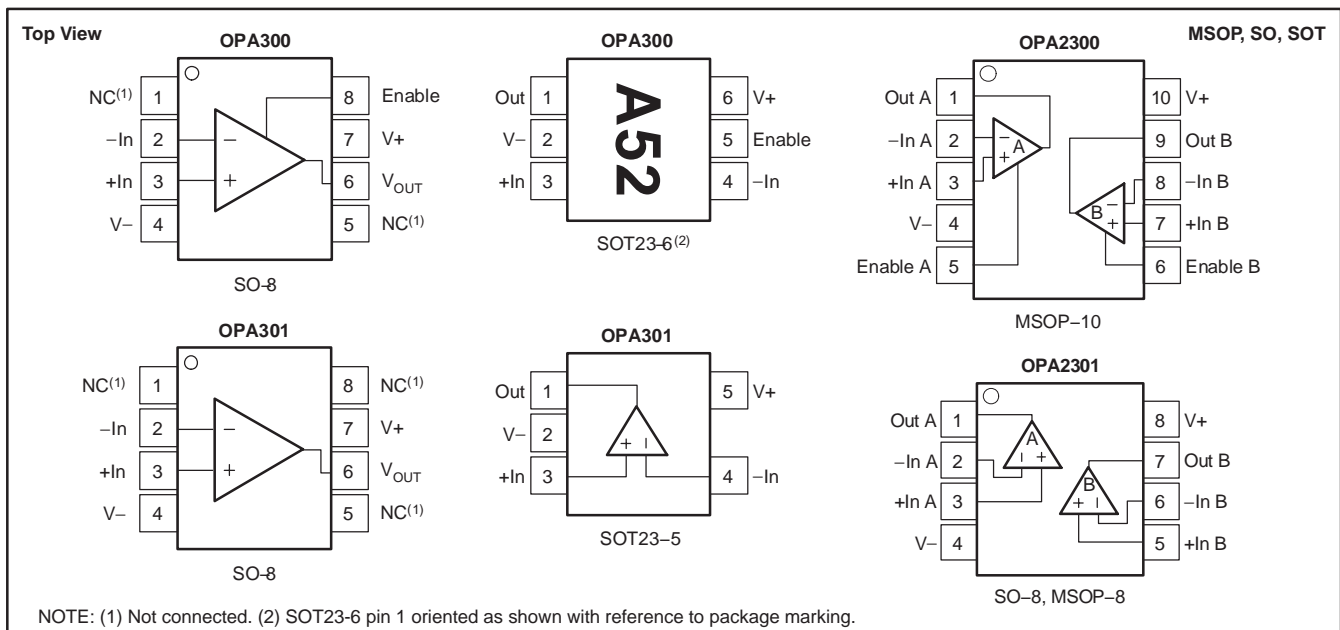
ELECTROSTATIC DISCHARGE SENSITIVITY



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PIN ASSIGNMENTS



ELECTRICAL CHARACTERISTICS: $V_S = 2.7V$ to $5.5V$

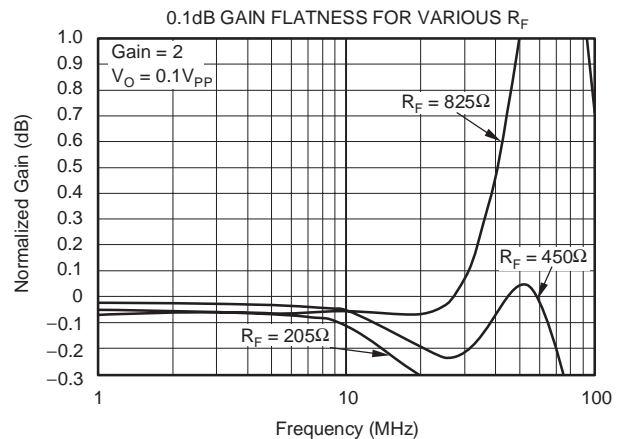
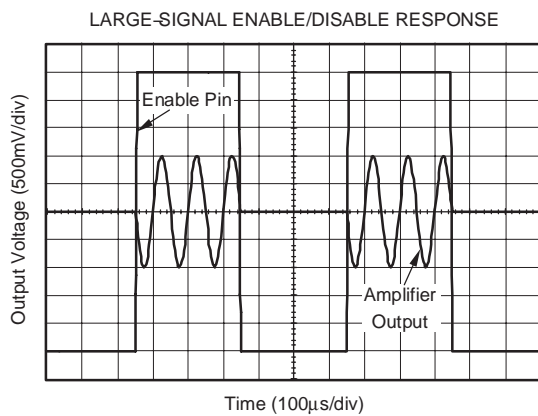
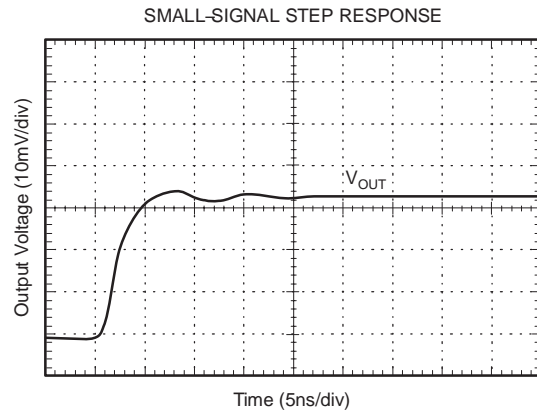
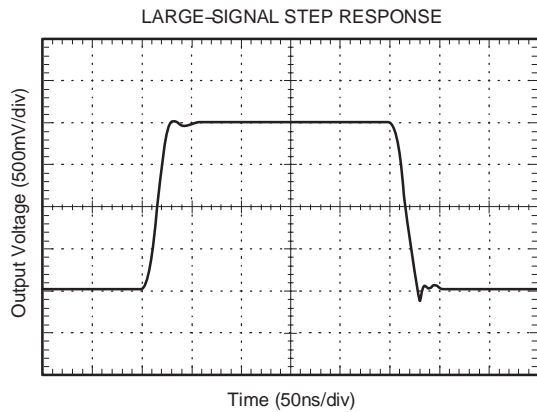
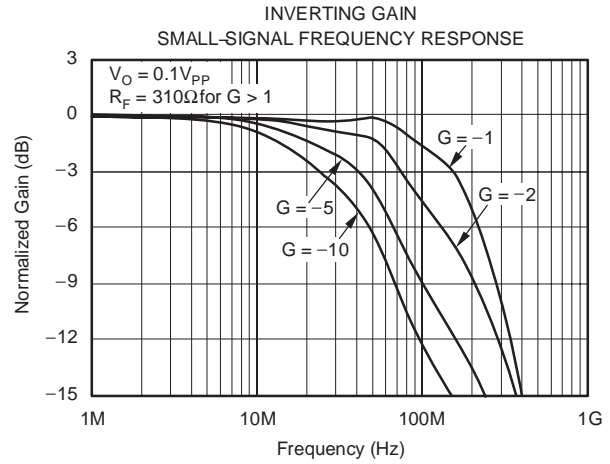
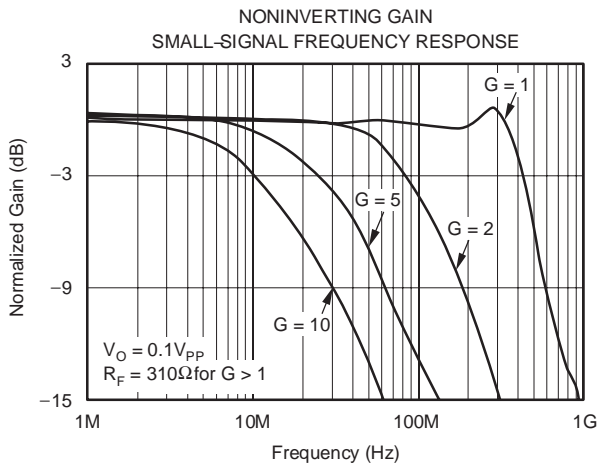
Boldface limits apply over the temperature range, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

All specifications at $T_A = +25^\circ\text{C}$, $R_L = 2k\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, and $V_{CM} = V_S/2$, unless otherwise noted.

PARAMETER	TEST CONDITIONS	OPA300, OPA301 OPA2300, OPA2301			UNITS
		MIN	TYP	MAX	
OFFSET VOLTAGE					
Input Offset Voltage Over Temperature Drift vs. Power Supply Channel Separation, dc $f = 5\text{MHz}$	V_{OS} dV_{OS}/dT PSRR $V_S = 2.7V$ to $5.5V$, $V_{CM} < (V+) - 0.9V$	$V_S = 5V$	1 2.5 50 140 100	5 7 200	mV mV $\mu\text{V}/^\circ\text{C}$ $\mu\text{V}/V$ dB dB
INPUT VOLTAGE RANGE					
Common-Mode Voltage Range Common-Mode Rejection Ratio	V_{CM} CMRR $(V-) - 0.2V < V_{CM} < (V+) - 0.9V$	$(V-) - 0.2$		$(V+) - 0.9$	V dB
INPUT BIAS CURRENT					
Input Bias Current Input Offset Current	I_B I_{OS}		± 0.1 ± 0.5	± 5 ± 5	pA pA
INPUT IMPEDANCE					
Differential Common-Mode			$10^{13} \parallel 3$ $10^{13} \parallel 6$		$\Omega \parallel \text{pF}$ $\Omega \parallel \text{pF}$
NOISE					
Input Voltage Noise, $f = 0.1\text{Hz}$ to 1MHz Input Voltage Noise Density, $f > 1\text{MHz}$ Input Current Noise Density, $f < 1\text{kHz}$ Differential Gain Error Differential Phase Error	e_n i_n	NTSC, $R_L = 150\Omega$ NTSC, $R_L = 150\Omega$	40 3 1.5 0.01 0.1		μV_{PP} $\text{nV}/\sqrt{\text{Hz}}$ $\text{fA}/\sqrt{\text{Hz}}$ % °
OPEN-LOOP GAIN					
Open-Loop Voltage Gain Over Temperature Over Temperature	A_{OL} $V_S = 5V$, $R_L = 2k\Omega$, $0.1V < V_O < 4.9V$ $V_S = 5V$, $R_L = 2k\Omega$, $0.1V < V_O < 4.9V$ $V_S = 5V$, $R_L = 100\Omega$, $0.5V < V_O < 4.5V$ $V_S = 5V$, $R_L = 100\Omega$, $0.5V < V_O < 4.5V$	95 90 95 90	106 106		dB dB dB dB
OUTPUT					
Voltage Output Swing from Rail Short-Circuit Current Open-Loop Output Impedance Capacitive Load Drive	I_{SC} R_O C_{LOAD}	$R_L = 2k\Omega$, $A_{OL} > 95\text{dB}$ $R_L = 100\Omega$, $A_{OL} > 95\text{dB}$ $I_O = 0$, $f = 1\text{MHz}$	75 300 70 20	100 500	mV mV mA Ω
FREQUENCY RESPONSE					
Gain-Bandwidth Product Slew Rate Settling Time, 0.01% 0.1% Overload Recovery Time Total Harmonic Distortion + Noise	GBW SR t_S THD+N	$G = +1$ $V_S = 5V$, $2V$ Step, $G = +1$ Gain = -1 $V_S = 5V$, $V_O = 3V_{PP}$, $G = +1$, $f = 1\text{kHz}$	150 80 90 30 30 0.003		MHz $V/\mu\text{s}$ ns ns ns %
POWER SUPPLY					
Specified Voltage Range Operating Voltage Range Quiescent Current (per amplifier) Over Temperature	V_S I_Q	$I_Q = 0$	2.7 9.5	5.5 12 13	V V mA mA
SHUTDOWN					
t_{OFF} t_{ON} V_L (shutdown) V_H (amplifier is active) I_{QSD} (per amplifier)			40 5 3		ns μs V V μA
TEMPERATURE RANGE					
Specified Range Operating Range Storage Range Thermal Resistance SO-8, MSOP-8, MSOP-10 SOT23-5, SOT23-6	θ_{JA}		-40 -55 -60 150 200	+125 +125 +150	$^\circ\text{C}$ $^\circ\text{C}$ $^\circ\text{C}$ $^\circ\text{C}/\text{W}$ $^\circ\text{C}/\text{W}$ $^\circ\text{C}/\text{W}$

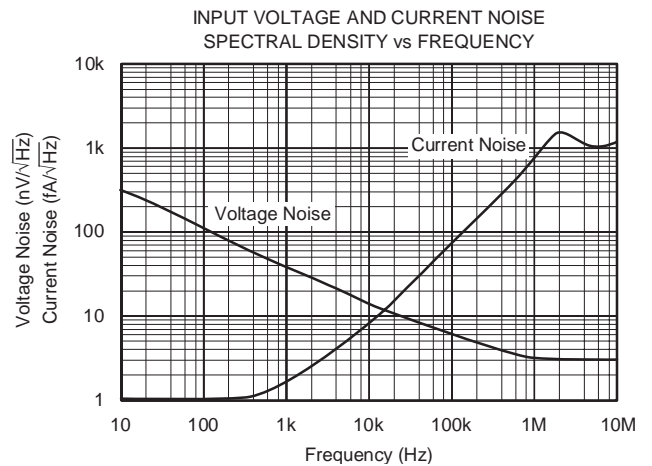
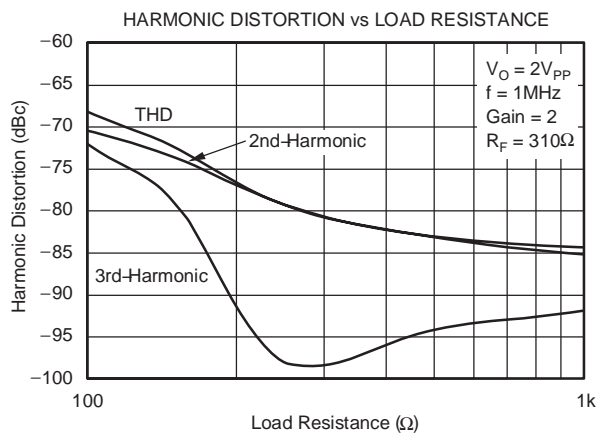
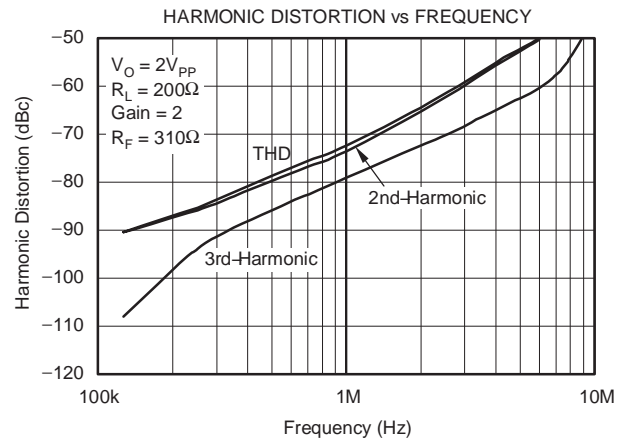
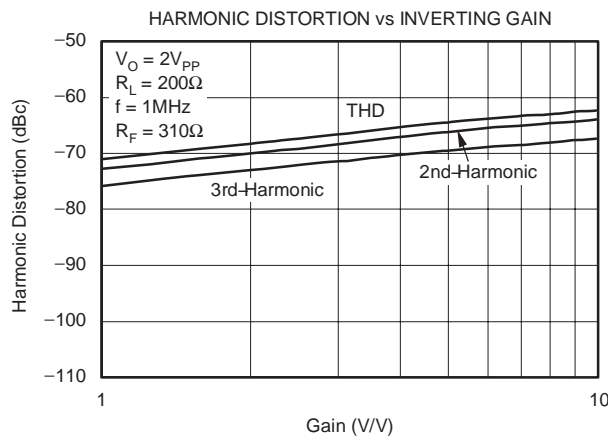
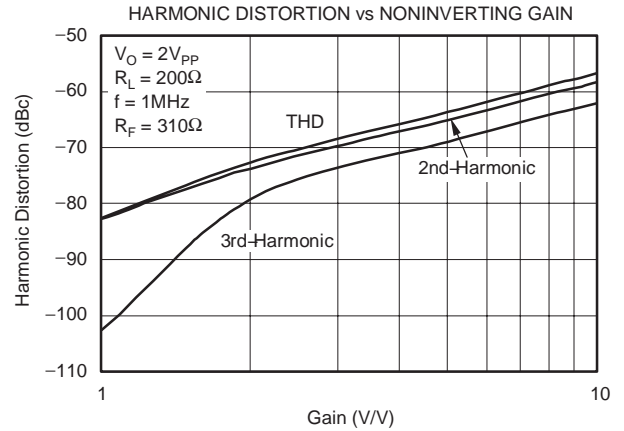
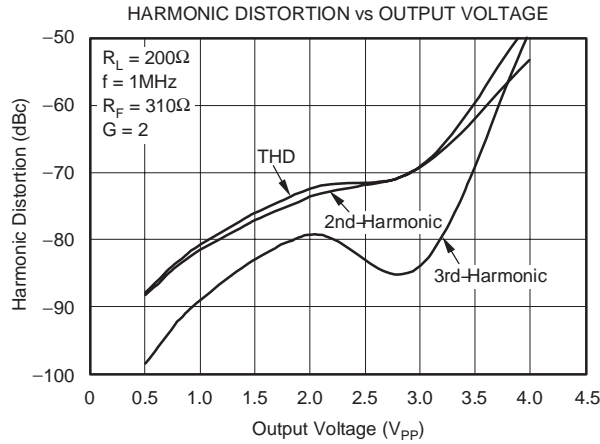
TYPICAL CHARACTERISTICS

All specifications at $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, and $R_L = 150\Omega$ connected to $V_S/2$ unless otherwise noted.



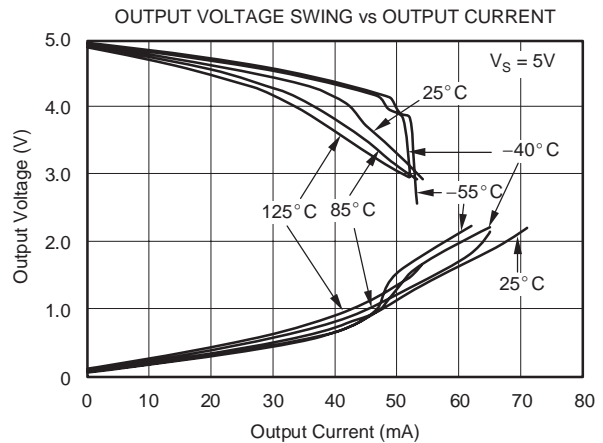
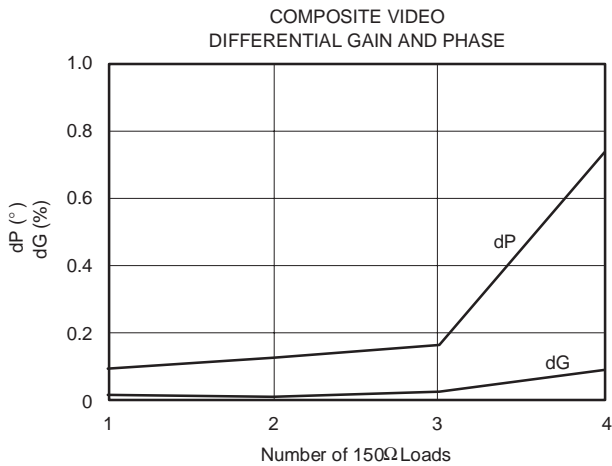
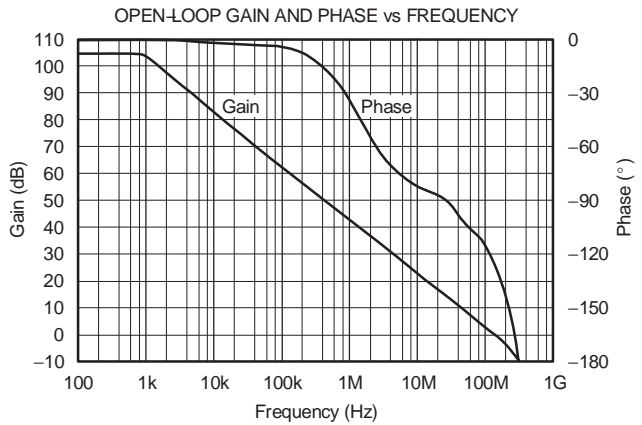
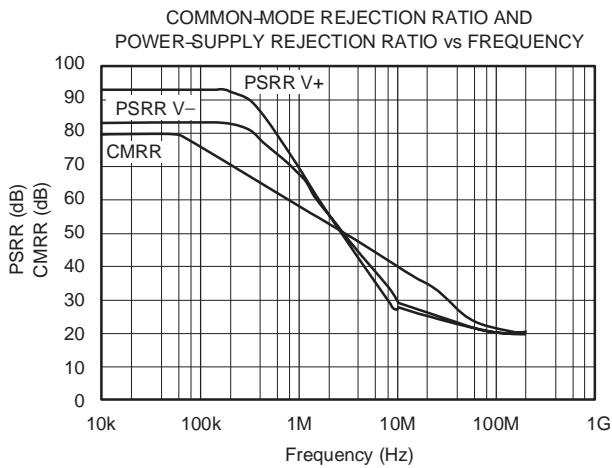
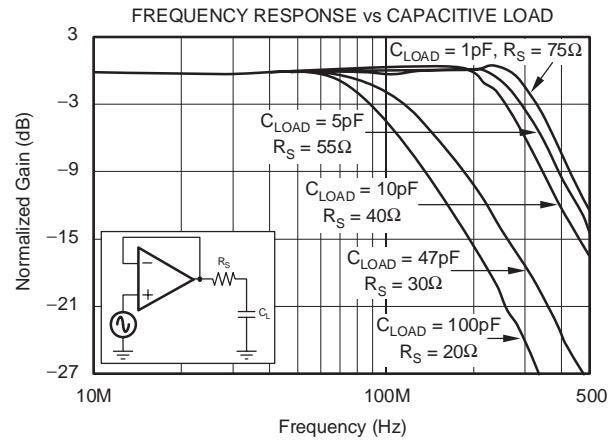
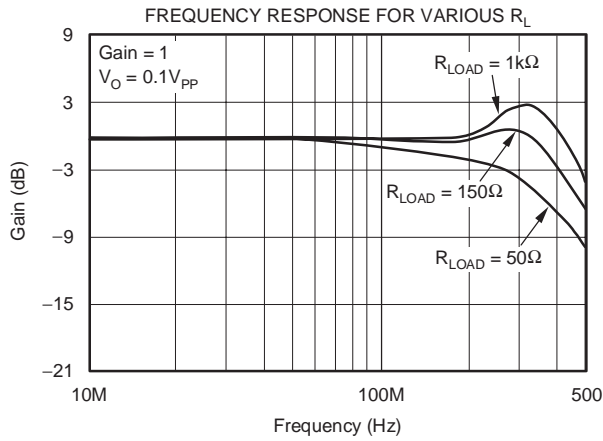
TYPICAL CHARACTERISTICS (continued)

All specifications at $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, and $R_L = 150\Omega$ connected to $V_S/2$ unless otherwise noted.



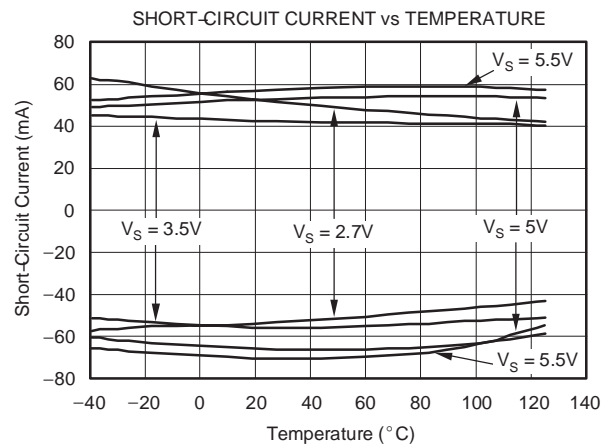
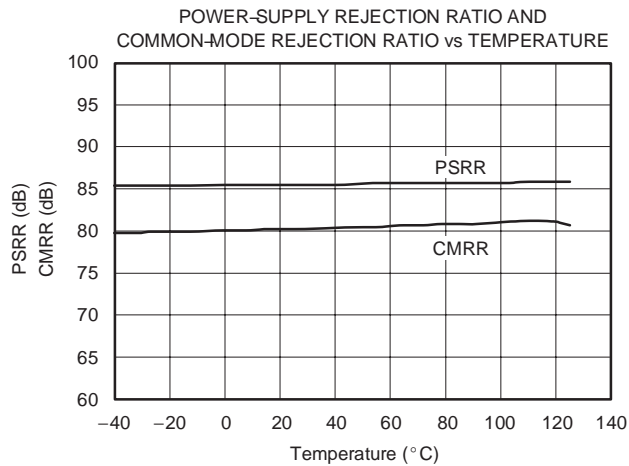
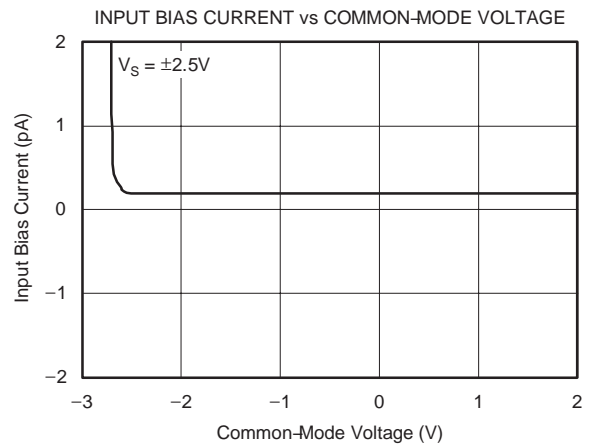
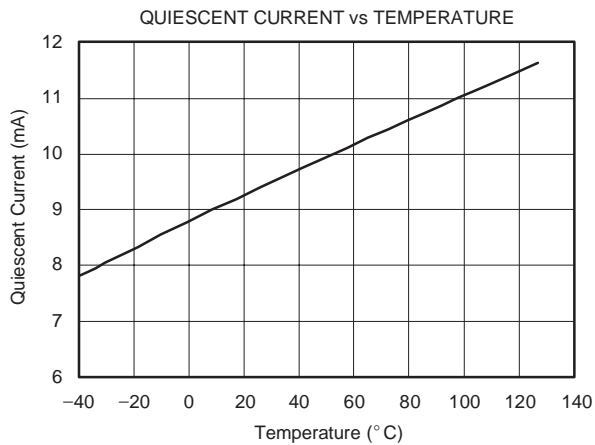
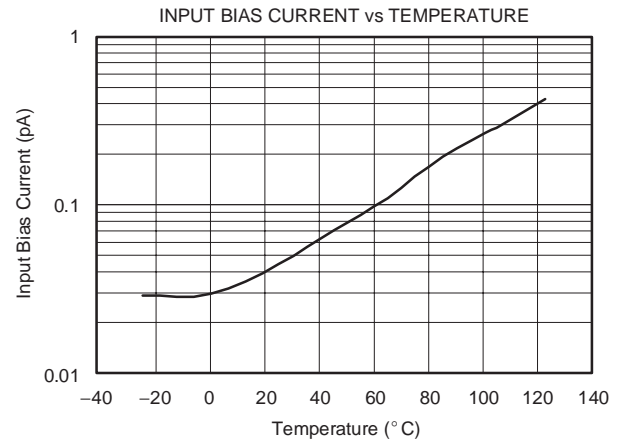
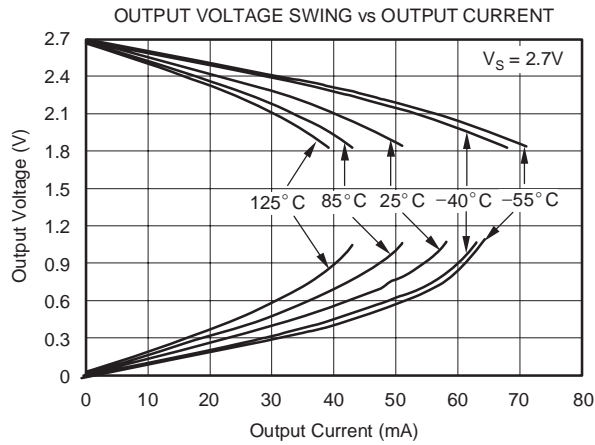
TYPICAL CHARACTERISTICS (continued)

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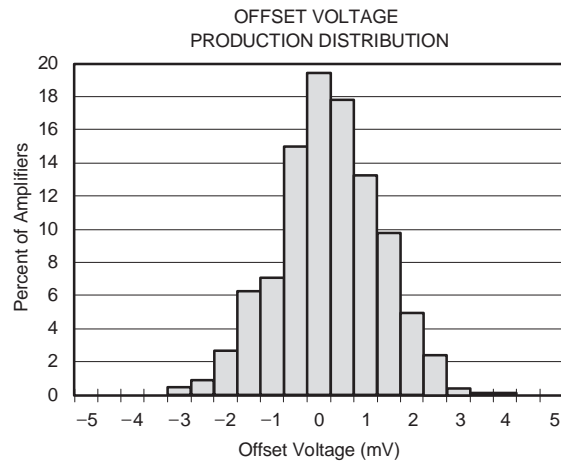
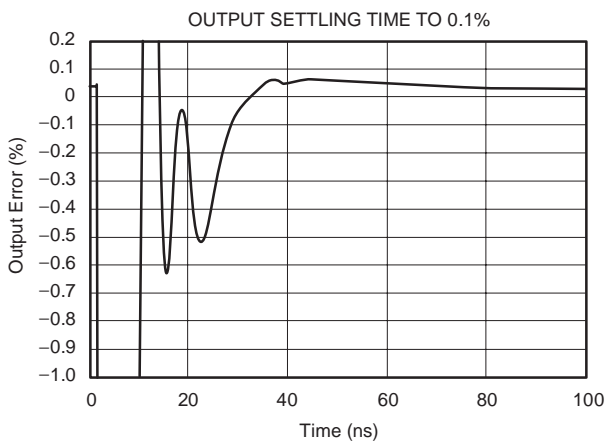
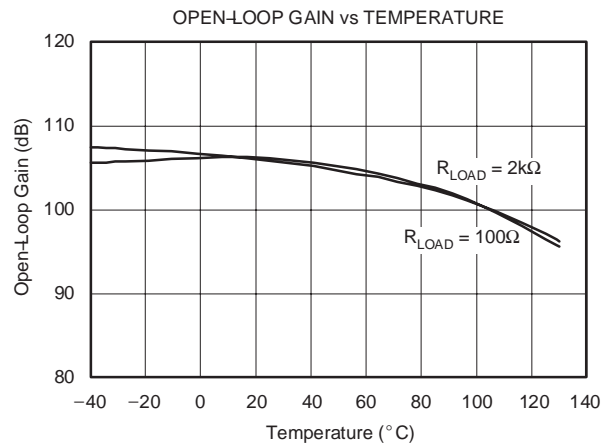
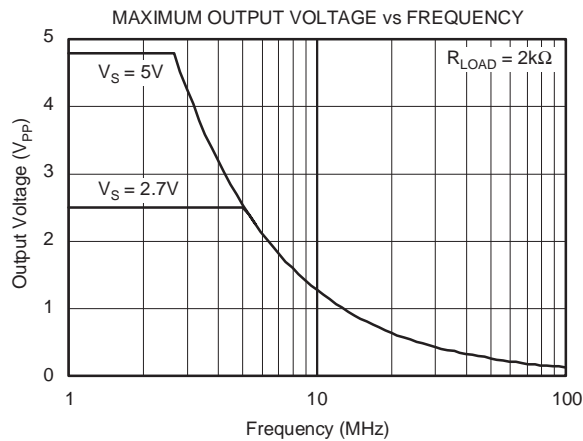
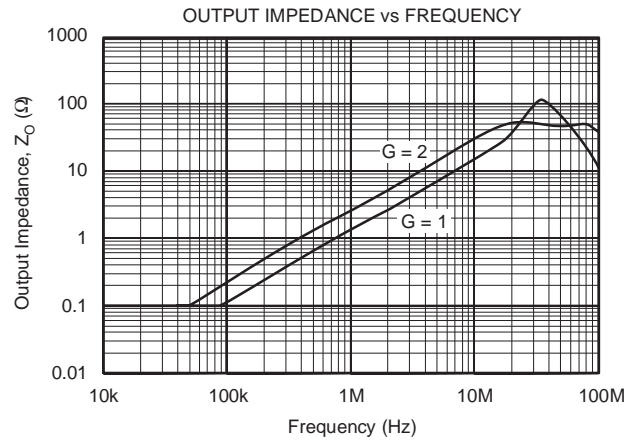
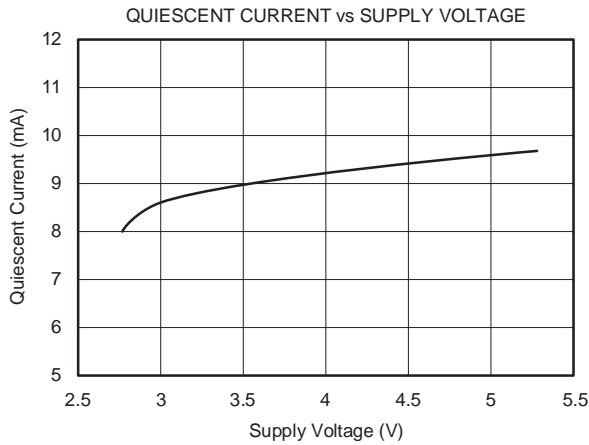
TYPICAL CHARACTERISTICS (continued)

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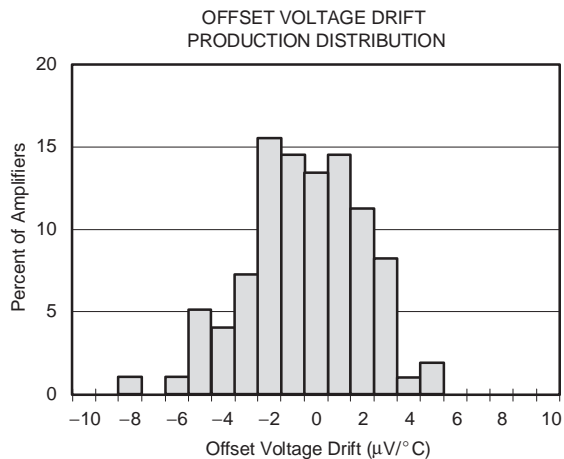
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All specifications at $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, and $R_L = 150\Omega$ connected to $V_S/2$ unless otherwise noted.



TYPICAL CHARACTERISTICS (continued)

All specifications at $T_A = 25^\circ\text{C}$, $V_S = 5\text{V}$, and $R_L = 150\Omega$ connected to $V_S/2$ unless otherwise noted.



APPLICATIONS INFORMATION

The OPA300 and OPA301 series of single-supply CMOS op amps are designed to interface with high-speed 16-bit analog-to-digital converters (ADCs). Featuring wide 150MHz bandwidth, fast 150ns settling time to 16 bits, and high open loop gain, this series offers excellent performance in a small SO-8 and tiny SOT23 packages.

THEORY OF OPERATION

The OPA300 and OPA301 series op amps use a classic two-stage topology, shown in Figure 1. The differential input pair is biased to maximize slew rate without compromising stability or bandwidth. The folded cascode adds the signal from the input pair and presents a differential signal to the class AB output stage. The class AB output stage allows rail-to-rail output swing, with high-impedance loads ($> 2k\Omega$), typically 100mV from the supply rails. With 10Ω loads, a useful output swing can be achieved and still maintain high open-loop gain. See the typical characteristic *Output Voltage Swing vs Output Current*.

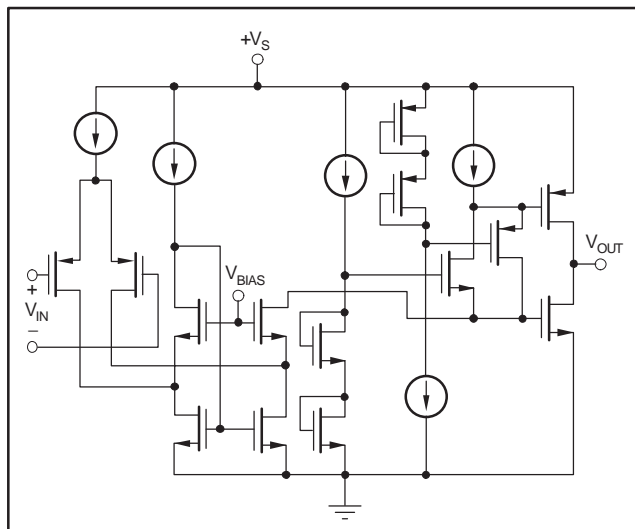


Figure 1. OPA30x Classic Two-Stage Topology

OPERATING VOLTAGE

OPA300/OPA301 series op amp parameters are fully specified from +2.7V to +5.5V. Supply voltages higher than 5.5V (absolute maximum) can cause permanent damage to the amplifier. Many specifications apply from -40°C to $+125^{\circ}\text{C}$. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Characteristics.

PCB LAYOUT

As with most high-speed operational amplifiers, board layout requires special attention to maximize AC and DC performance. Extensive use of ground planes, short lead lengths, and high-quality bypass capacitors will minimize leakage that can compromise signal quality. Guard rings applied with potential as near to the input pins as possible help minimize board leakage.

INPUT AND ESD PROTECTION

All OPA300/OPA301 series op amps' pins are static-protected with internal ESD protection diodes tied to the supplies, as shown in Figure 2. These diodes will provide overdrive protection if the current is externally limited to 10mA, as stated in the Absolute Maximum Ratings. Any input current beyond the Absolute Maximum Ratings, or long-term operation at maximum ratings, will shorten the lifespan of the amplifier.

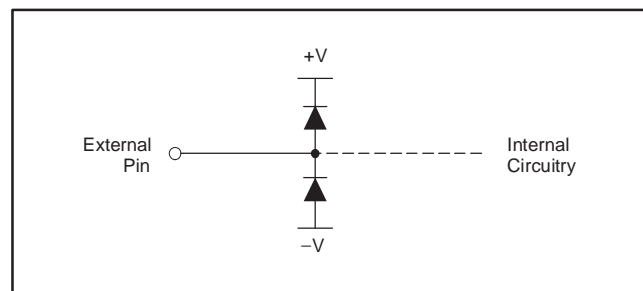


Figure 2. ESD Protection Diodes

ENABLE FUNCTION

The shutdown function of the OPA300 and OPA2300 is referenced to the negative supply voltage of the operational amplifier. A logic level HIGH enables the op amp. A valid logic HIGH is defined as 2.5V above the negative supply applied to the enable pin. A valid logic LOW is defined as $< 0.8\text{V}$ above the negative supply pin. If dual or split power supplies are used, care should be taken to ensure logic input signals are properly referred to the negative supply voltage. If this pin is not connected to a valid high or low voltage, the internal circuitry will pull the node high and enable the part to function.

The logic input is a high-impedance CMOS input. For battery-operated applications, this feature may be used to greatly reduce the average current and extend battery life. The enable time is $10\mu\text{s}$; disable time is $1\mu\text{s}$. When disabled, the output assumes a high-impedance state. This allows the OPA300 to be operated as a gated amplifier, or to have its output multiplexed onto a common analog output bus.

DRIVING CAPACITIVE LOADS

When using high-speed operational amplifiers, it is extremely important to consider the effects of capacitive loading on amplifier stability. Capacitive loading will interact with the output impedance of the operational amplifier, and depending on the capacitor value, may significantly decrease the gain bandwidth, as well as introduce peaking. To reduce the effects of capacitive loading and allow for additional capacitive load drive, place a series resistor between the output and the load. This will reduce available bandwidth, but permit stable operation with capacitive loading. Figure 3 illustrates the recommended relationship between the resistor and capacitor values.

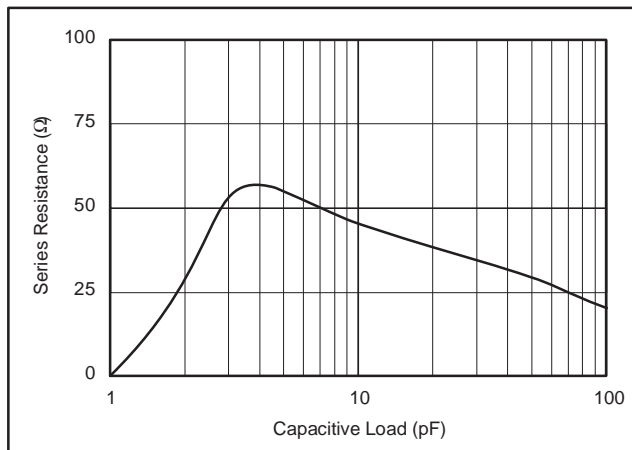


Figure 3. Recommended R_S and C_L Combinations

Amplifiers configured in unity gain are most susceptible to stability issues. The typical characteristic, *Frequency Response vs Capacitive Load*, describes the relationship between capacitive load and stability for the OPA300/OPA301 series. In unity gain, the OPA300/OPA301 series is capable of driving a few picofarads of capacitive load without compromising stability. Board level parasitic capacitance can often fall into the range of a picofarad or more, and should be minimized through good circuit-board layout practices to avoid compromising the stability of the OPA300/OPA301. For more information on detecting parasitics during testing, see the Application Note *Measuring Board Parasitics in High-Speed Analog Design* (SBOA094), available at the TI web site www.ti.com.

DRIVING A 16-BIT ADC

The OPA300/OPA301 series feature excellent THD+noise, even at frequencies greater than 1MHz, with a 16-bit settling time of 150ns. Figure 4 shows a total single supply solution for high-speed data acquisition. The OPA300/OPA301 directly drives the ADS8401, a 1.25 mega sample per second (MSPS) 16-bit data converter. The OPA300/OPA301 is configured in an inverting gain of 1, with a 5V single supply. Results of the OPA300/OPA301 performance are summarized in Table 1.

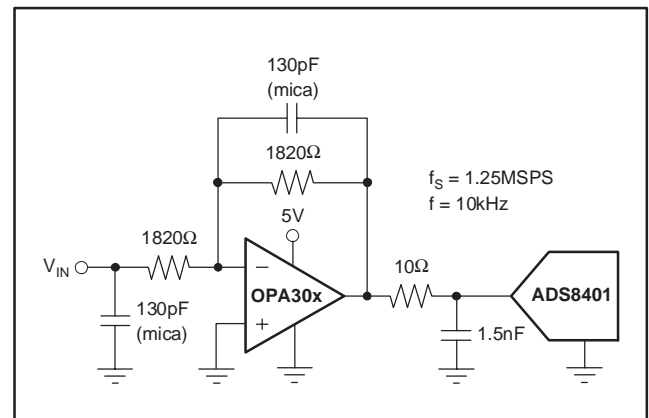


Figure 4. The OPA30x Drives the 16-Bit ADS8401

PARAMETER	RESULTS (f = 10kHz)
THD	-99.3dB
SFDR	101.2dB
THD+N	84.2dB
SNR	84.3dB

Table 1. OPA30x Performance Results Driving a 1.25MSPS ADS8401

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2300AIDGSR	ACTIVE	VSSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	C01	Samples
OPA2300AIDGSRG4	ACTIVE	VSSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	C01	Samples
OPA2300AIDGST	ACTIVE	VSSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	C01	Samples
OPA2301AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 2301A	Samples
OPA2301AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 2301A	Samples
OPA2301AIDGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OAWM	Samples
OPA2301AIDGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OAWM	Samples
OPA2301AIDGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	OAWM	Samples
OPA2301AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 2301A	Samples
OPA300AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 300A	Samples
OPA300AIDBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A52	Samples
OPA300AIDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A52	Samples
OPA300AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 300A	Samples
OPA301AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 301A	Samples
OPA301AIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AUP	Samples
OPA301AIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AUP	Samples
OPA301AIDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	AUP	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA301AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 301A	Samples
OPA301AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 301A	Samples
OPA301AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA 301A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2300AIDGSR	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2300AIDGST	VSSOP	DGS	10	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2301AIDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2301AIDGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2301AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA301AIDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA301AIDBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA301AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal


Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2300AIDGSR	VSSOP	DGS	10	2500	367.0	367.0	35.0
OPA2300AIDGST	VSSOP	DGS	10	250	210.0	185.0	35.0
OPA2301AIDGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2301AIDGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2301AIDR	SOIC	D	8	2500	367.0	367.0	35.0
OPA301AIDBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
OPA301AIDBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA301AIDR	SOIC	D	8	2500	367.0	367.0	35.0

MECHANICAL DATA

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
-  Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

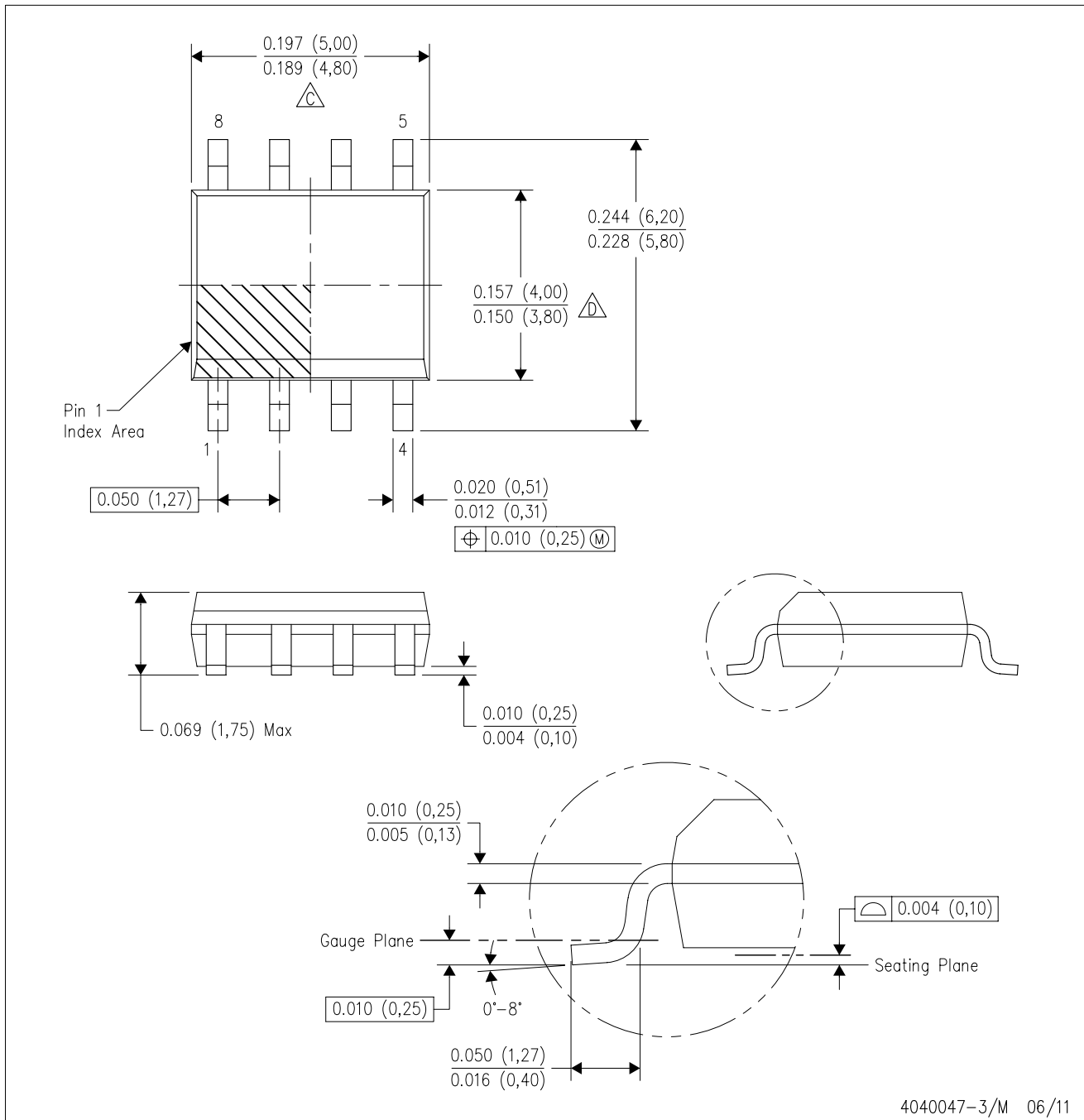
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE

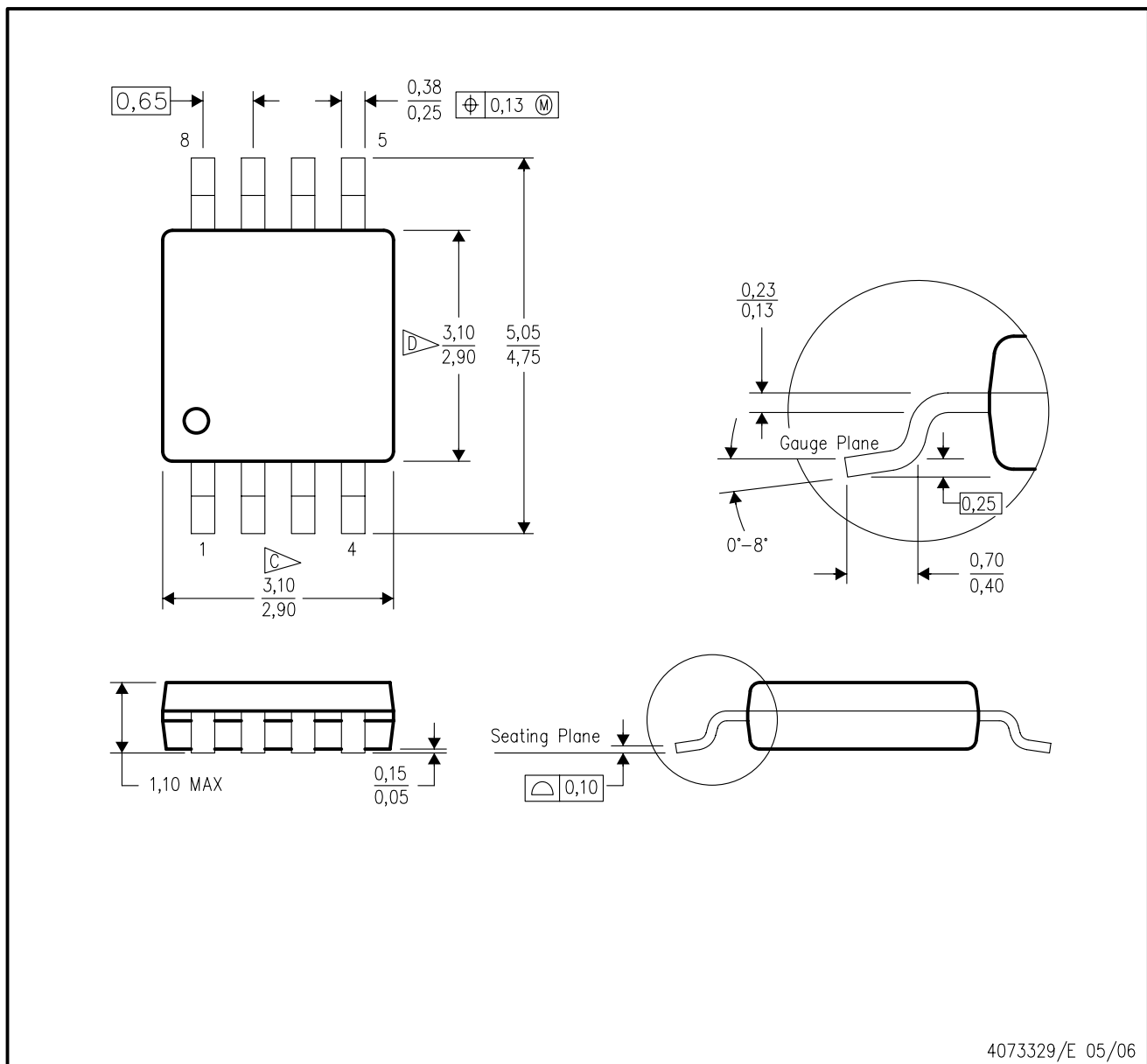


4209593-3/C 08/11

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DGS (S-PDSO-G10)

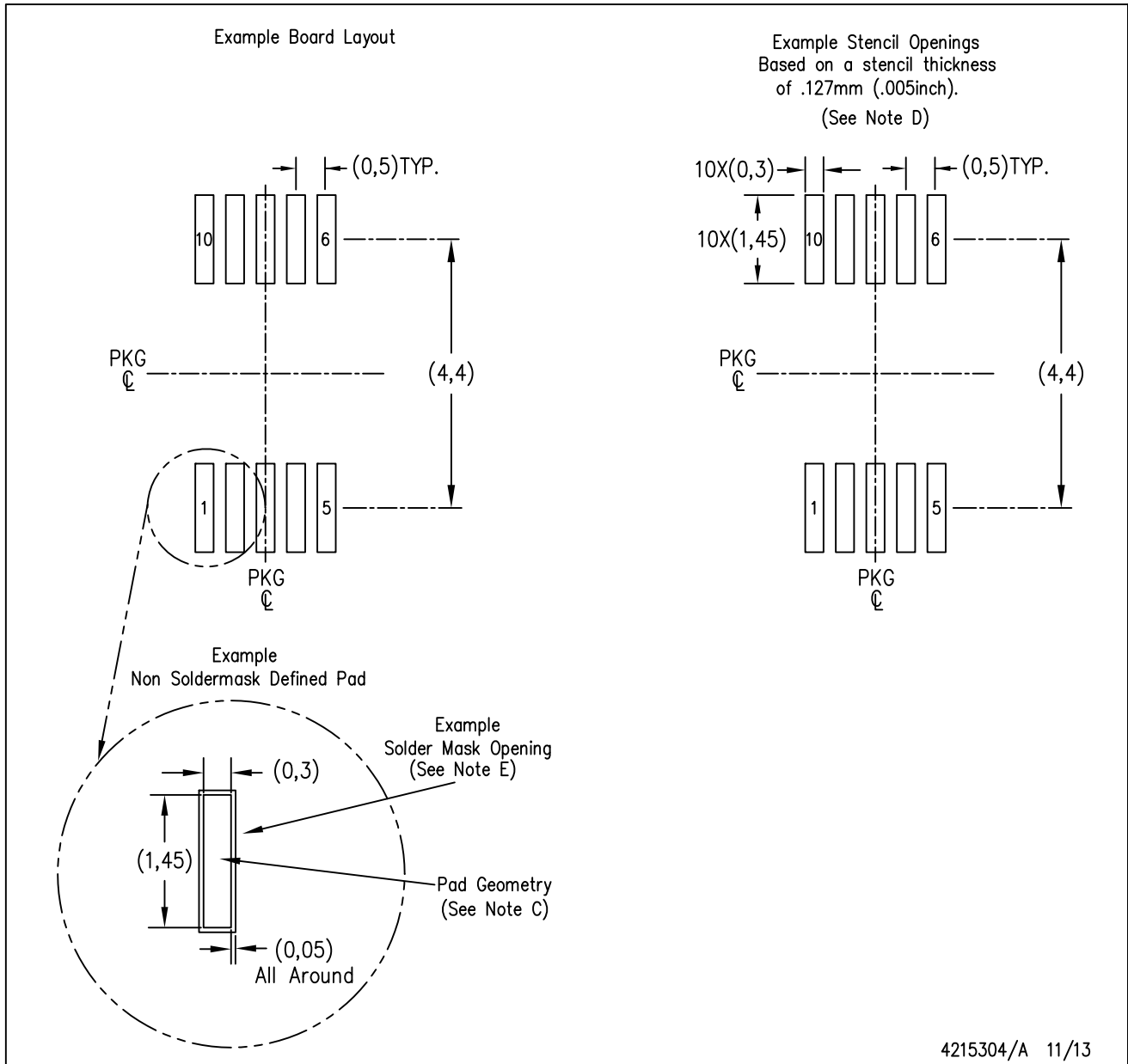
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-187 variation BA.

DGS (S-PDSO-G10)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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